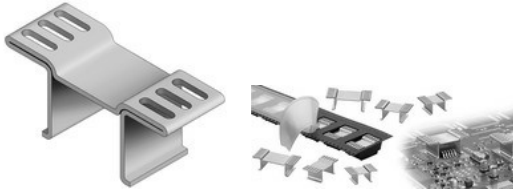


Data sheet Product FK 244 08 D PAK



Board Level heatsinks > Heatsinks for D PAK and others

- direct PCB mounting thru solderable surface
- available standard packing: loose parts (**bulk goods**) or reel (**TR** = tape and reel)
- **tape width:** 44 mm, **reel diameter:** 330 mm, **quantity:** FK 244 08 = 450, FK 244 13 = 200

Features

for transistor

- D PAK (TO 252)
- D² PAK (TO 263)
- D³ PAK (TO 268)
- SO-8
- SO-14
- SO-16
- Power SO 10
- SOT 223

width B	23 mm
height	10 mm
length	8 mm
thermal resistance R _{th}	31.5 K/W
surface	solderable surface
material	copper (Cu)
material thickness	0.6 mm

Technical Drawing

